

STRUCTURE      Silicon Monolithic Integrated Circuit  
 TYPE              Single Channel Series Regulator Driver IC  
 PRODUCT SERIES    **BD3501FVM**  
 FEATURES          •Non Rush Current on Start up (NRCS)  
                          •N channel MOSFET driver

## ○ ABSOLUTE MAXIMUM RATINGS (Ta=25°C)

PARAMETER	SYMBOL	LIMIT	UNIT
Supply Voltage	VCC	7 *1	V
Drain Voltage (VIN)	VIN	7	V
Enable Input Voltage	Ven	7	V
Power Dissipation	Pd	437.5 *2	mW
Operating Temperature Range	Topr	-40~+100	°C
Storage Temperature Range	Tstg	-55~+150	°C
Maximum Junction Temperature	Tjmax	+150	°C

\*1 Operating temperature range should not exceed Tjmax=150°C

\*2 Pd derating at 3.5mW/°C for temperature above Ta=25°C

## ○ RECOMMENDED OPERATING CONDITIONS (Ta=25°C)

PARAMETER	SYMBOL	MIN	MAX	UNIT
Supply Voltage	VCC	4.5	5.5	V
Drain Voltage (VIN)	VIN	Vo × 1.15	5.5	V
Enable Input Voltage	Ven	-0.3	5.5	V
Capacitor on NRCS Terminal	CNRCS	0.001	1	μF
Capacitor on SCP Terminal	CSCP	0.001	1	μF

★ This product should not be used within a radioactive environment

Status of this document

The Japanese version of this document is the official specification.

This translated version is intended only as a reference, to aid in understanding the official version.

If there are any differences between the original and translated versions of this document, the official Japanese language version takes priority.

○ ELECTRICAL CHARACTERISTICS (Unless otherwise specified, Ta=25°C VCC=5V Vin=3.3V Ven=3V)

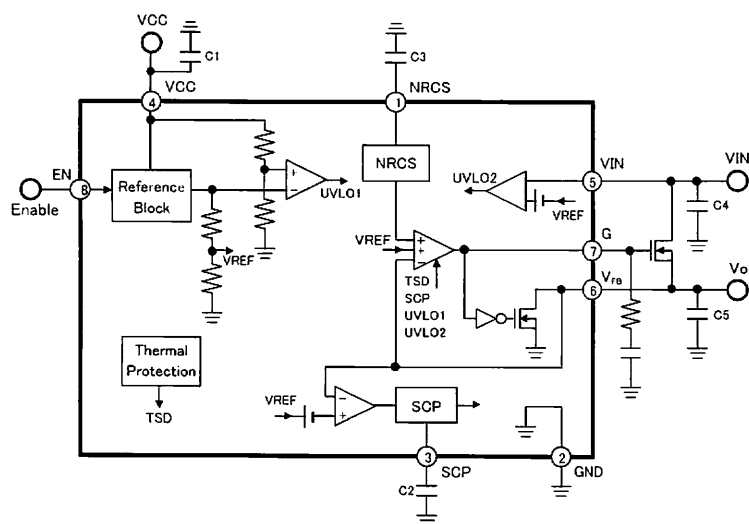
PARAMETER	SYMBOL	LIMIT			UNIT	CONDITIONS
		MIN	TYP	MAX		
Bias Current	ICC	-	0.8	1.6	mA	
Shut Down Mode Current	IST	-	0	10	uA	Ven=0V
Output Voltage 1	Vo1	1.485	1.500	1.515	V	Io=50mA
Output Voltage 2	Vo2	1.455	1.500	1.545	V	Vcc=4.5V to 5.5V ,Io=0 to 3A Ta=-10°C to 100°C(※)
Line Regulation	Reg.I	-	0.1	0.5	%/V	VCC=4.5V to 5.5V
Load Regulation	Reg.L	-	0.5	10	mV	Io=0 to 3A
[Enable]						
High Level Enable Input Voltage	Enhi	2	-	Vcc	V	
Low Level Enable Input Voltage	Enlow	-0.3	-	0.8	V	
Enable Pin Input Current	Ien	-	7	10	uA	Ven=3V
[NRCS]						
NRCS Charge Current	Inrcs	14	20	26	uA	Vnracs=0.5V,VCC=4.5V to 5.5V Ta=-10°C to 100°C (※)
NRCS Standby Voltage	Vnracs	-	0	50	mV	Ven=0V
[Voltage Feed Back]						
VFB Input Bias Current	IFB	-	0.7	1.2	mA	Ven=3V
VFB Standby Current	FBSTB	150	-	-	mA	Ven=0V,VFB=1V
[Output MOSFET Driver]						
MOSFET Driver Source Current	IGSO	0.5	1	1.5	mA	VFB=Vo-0.1V,G=Vo+1V
MOSFET Driver Sink Current	IGSI	2	3	4	mA	VFB=Vo+0.1V,G=Vo+1V
[UVLO]						
VCC UVLO	VccUVLO	4.2	4.35	4.5	V	Vcc:Sweep up
VCC UVLO Hysteresis	Vcchys	100	160	220	mV	Vcc:Sweep down
VIN UVLO	VINUVLO	Vo × 1.05	Vo × 1.1	Vo × 1.15	V	VIN:Sweep up
VIN UVLO Hysteresis	VINhys	80	130	180	mV	VIN:Sweep down
[SCP]						
SCP Charge Current	Iscpch	14	20	26	uA	VSCP=0.5V,VCC=4.5V to 5.5V Ta=-10°C to 100°C (※)
SCP Discharge Current	IscpDi	0.5	-	-	mA	VSCP=0.5V
SCP Threshold Voltage	Vscpth	1.2	1.3	1.4	V	
Short Detect Voltage	Vscp	Vo × 0.6	Vo × 0.7	Vo × 0.8	V	
SCP Stand-by Voltage	VSTB	-	0	50	mV	

(※) Design Guarantee

☐ BLOCK DIAGRAM



☐ BLOCK DIAGRAM



☐ Pin number    Pin name

Pin number	Pin name
1	NRCS
2	GND
3	SCP
4	VCC
5	VIN
6	VFB
7	G
8	EN

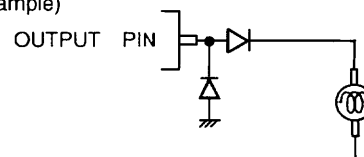
## NOTES FOR USE

- (1) Absolute maximum range  
Although the quality of this product is rigorously controlled, and circuit operation is guaranteed within the operation ambient temperature range, the device may be destroyed when applied voltage or operating temperature exceeds its absolute maximum rating. Because the failure mode (such as short mode or open mode) cannot be identified in this instance, it is important to take physical safety measures such as fusing if a specific mode in excess of absolute rating limits is considered for implementation.
- (2) Ground potential  
Make sure the potential for the GND pin is always kept lower than the potentials of all other pins, regardless of the operating mode, including transient conditions.
- (3) Thermal Design  
Provide sufficient margin in the thermal design to account for the allowable power dissipation (Pd) expected in actual use.
- (4) Using in the strong electromagnetic field  
Use in strong electromagnetic fields may cause malfunctions.
- (5) ASO  
Be sure that the output transistor for this IC does not exceed the absolute maximum ratings or ASO value.
- (6) Thermal shutdown circuit  
The IC is provided with a built-in thermal shutdown (TSD) circuit. When chip temperature reaches the threshold temperature shown below, output goes to a cut-off (open) state. Note that the TSD circuit is designed exclusively to shut down the IC in abnormal thermal conditions. It is not intended to protect the IC per se or guarantee performance when extreme heat occurs. Therefore, the TSD circuit should not be employed with the expectation of continued use or subsequent operation once TSD is operated.

TSD ON temperature [°C] (typ.)	Hysteresis temperature [°C] (typ.)
175	15

- (7) GND pattern  
When both a small-signal GND and high current GND are present, single-point grounding (at the set standard point) is recommended, in order to separate the small-signal and high current patterns, and to be sure the voltage change stemming from the wiring resistance and high current does not cause any voltage change in the small-signal GND. In the same way, care must be taken to avoid wiring pattern fluctuations in any connected external component GND.
- (8) Output Capacitor (C5)  
Mount an output capacitor between VFB and GND for stability purposes. The output capacitor is for the open loop gain phase compensation and reduces the output voltage load regulation. If the capacitor value is not large enough, the output voltage may oscillate. And if the equivalent series resistance (ESR) is too large, the output voltage rise/drop increases during a sudden load change. A 220uF polymer capacitor is recommended. However, the stability depends on the characteristics of temperature, load, the gate capacitance of the external MOSFET, and the mutual conductance (gm). And if a small ESR capacitor such as a ceramic capacitor is utilized, the output voltage may oscillate due to lack of phase margin. In this case, measures can be taken by adding a capacitor and a resistor in series with this capacitor between the gate of MOSFET and GND. Please confirm operation across a variety of temperature, load conditions, and MOSFET characteristics.
- (9) Input Capacitor (C1, C4)  
The input capacitor reduces the output impedance of the voltage supply source connected in the VCC and VIN. If the output impedance of this power supply increases, the input voltage (VCC,VIN) may become unstable. This may result in the output voltage oscillation or lowering ripple rejection. A low ESR 10uF capacitor with minimal susceptibility to temperature is preferable, but stability depends on power supply characteristics, the substrate wiring pattern, and the parasitic capacitor between Gate and Drain of MOSFET. Please confirm operation across a variety of temperature, load, and MOSFET conditions.
- (10) NRCS (Non Rush Current on Start-up) Setting (C3)  
The NRCS function is built in this IC to prevent rush current from going through the load (VIN to Vo) for start-up. The constant current comes from the NRCS pin when EN is high or UVLO function is deactivated. Temporary reference voltage is made proportional to time due to current charge the NRCS pin capacitor and make output voltage start up proportional to this reference voltage. To obtain a stable NRCS delay time, a capacitor (X5R or X7R) with susceptibility to temperature is recommended.
- (11) SCP Capacitor Setting (C2)  
Timer latch short circuit protection circuit is built in this IC to protect the breakdown of the power MOSFET caused by rush current when the output is shorted to GND (NRCS is also working at the same time.). This function becomes active when the output voltage level goes under by 30% of specified Vout. The constant current comes from the SCP pin in this case. When the reference voltage made by the current charge of the SCP pin hits 1.3V (Typ.), the gate voltage becomes low. To obtain a stable SCP delay time, a capacitor (X5R or X7R) with susceptibility to temperature is recommended.  
If SCP function is not utilized on a actual application, short SCP pin to GND.  
When the output is shorted to GND, the gate voltage of the MOSFET is pulled up to VCC. And a very high current keeps going from VCC to the output through the MOSFET until the timer latch SCP function is activated. If the power supply connected to VIN does not have enough current ability, VIN voltage decreases and the UVLO circuit is activated. Consequently, incomplete latch operation is possible. In this case, connect a resistor between the drain of the MOSFET and VIN.
- (12) Input Terminal (VCC,VIN,EN)  
The EN, VIN, and VCC are isolated. The UVLO protects incorrect operation when the voltage level of VIN and VCC are low. The output becomes high when these pins reach the individual threshold level independent of the start-up pin order.
- (13) Maximum Output Current (Maximum Load)  
The maximum output current of the power supply utilizing the IC depends on external MOSFET. The MOSFET should be chosen based on a required power supply characteristics for an actual application.
- (14) Please add a protection diode when a large inductance component is connected to the output terminal, and reverse-polarity power is possible at startup or in output OFF condition.

(Example)



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